



Material Content Data Sheet



Sales Product Name		IPP039N10N5		Issued		4. October 2018		
MA#		MA001710250						
Package		PG-TO220-3-1		Weight*		2035.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.268	0.16	0.16	1605	1605
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.07	40.12	400480	401001
	non noble metal	aluminium	7429-90-5	11.331	0.56	0.56	5566	5566
wire	non noble metal	aluminium	7429-90-5	11.331	0.56	0.56	5566	5566
encapsulation	organic material	carbon black	1333-86-4	8.849	0.43		4346	
	plastics	epoxy resin	-	97.335	4.78		47810	
	inorganic material	silicondioxide	60676-86-0	483.725	23.76	28.97	237599	289755
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10542	10542
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.061	0.00		30	
	noble metal	silver	7440-22-4	0.076	0.00		37	
	non noble metal	lead	7439-92-1	2.907	0.14	0.14	1428	1495
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.95	28.99	289538	289915
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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